

tabletop hotplate.

Stand-alone device for temperatures from 30 – 300 °C

The compact amcoss laboratory-hotplate is the perfect, flexible device for single process steps or for small-lot production of substrates sizes between 2" and 300 mm in R&D laboratories.

amt **amt**
200 **300**



Beneficial standard highlights_

The usage of high-quality, standard industry-components ensures reliability in operation, long lifetime, good serviceability, and a very attractive price-performance-ratio.

// One hotplate for different wafer and substrate sizes (2", 3", 100 mm, 150 mm, 200 mm, and 300 mm) and even special substrate specifications (square, rectangular, etc.)

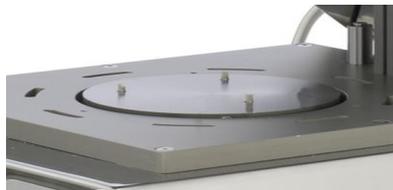
// Optimal temperature uniformity: +/- 0.5 K ≤ 100 °C, +/- 1 % > 100 °C measured on a 200 mm wafer

// Efficient exhaust which can be adjusted manually without difficulty

// The standard maximum temperature is 200 °C



// 99 program recipes can be selected and adjusted (nominal temperature and processing time) directly on the integrated touch screen.



// Optionally, the hotplate can be equipped with 3 lift pins which hoist the wafer by pushing it at the backside. This simplifies removal of the substrate.



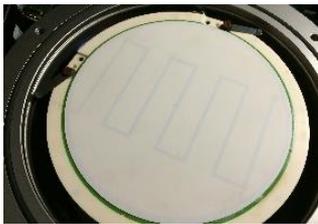
// The temperature control on the display enables monitoring of the process temperature at any time of the heating process.

SOPHISTICATED

Additional features, extra value_

Knowing about the differing needs and requirements of our customers, flexibility in the configuration of the amcoss laboratory-hotplate is our utmost priority. By offering a multitude of additional features which can be chosen and combined individually each customer will get an individual hotplate device.

- // **Lift pins:** various versions of lift pins are available
 - Pneumatic lift pins for different wafer sizes
 - Programmable, electrical lift pins for different wafer sizes – lifting height and time programmable via recipe
- // **Electronic exhaust alarm and display:** serves as a control system for the standard exhaust
- // **Proximity:** as standard, the substrate lies in full contact, but slackly on the hotplate. Additionally, following options are selectable:
 - Vacuum chuck: full contact of substrate to the hotplate with vacuum chucking
 - Fixed proximity: due to proximity balls, fixed proximity of substrate to the hotplate surface is 150 μ
 - Customized proximity: each individual substrate proximity is selectable via programmable lift pins
- // **N2 purge:** if an inert gas atmosphere is needed for special processes the N2 gas-purge option can be switched on
- // **High temperature hotplate:** heats up to a temperature of either 250 °C or 300 °C



Special hotplate



Hotplate with wafer

COMPONENT OVERVIEW

- 1 Hotplate
(optional: high temperature hotplate)
- 2 Lift pin impetus
- 3 LCD touch panel for the programming of the 99 recipes
- 4 3 wafer lift pins
- 5 Temperature control module

Use our product configurator to compile your individual amt hotplate:

